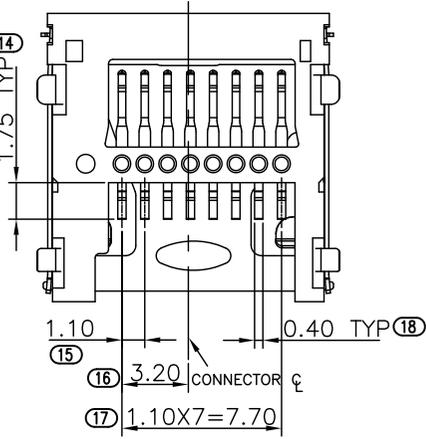
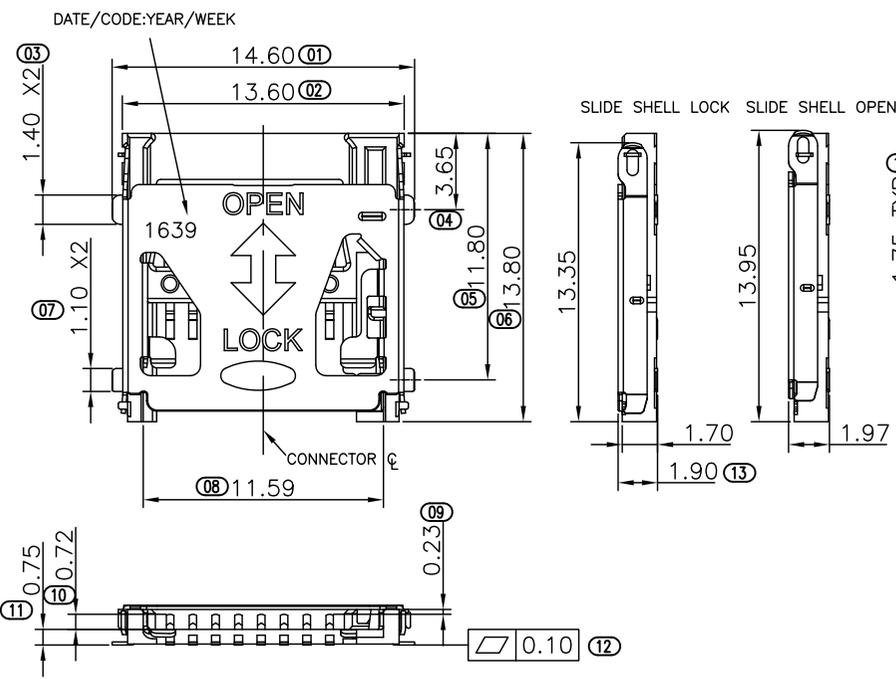
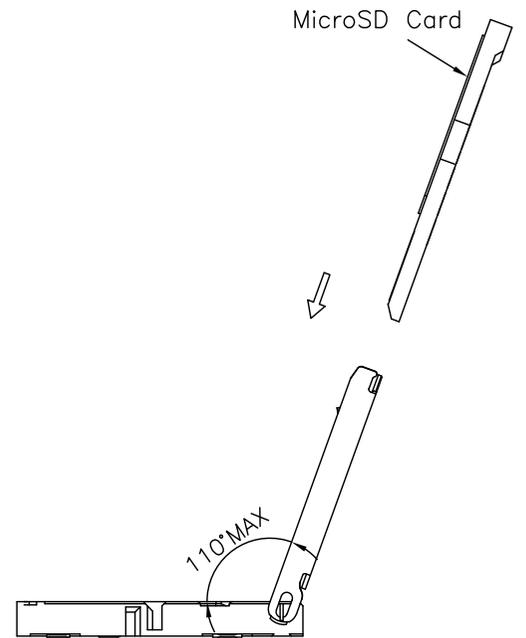
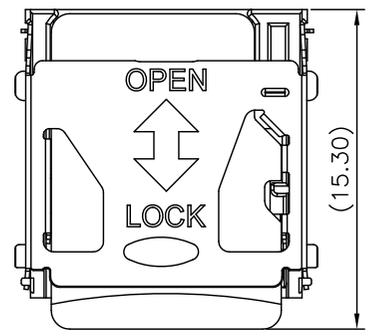
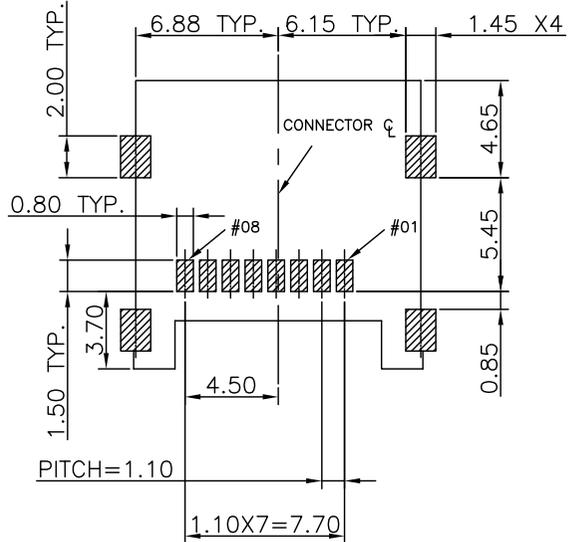
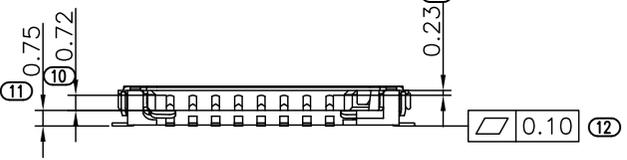


REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	11/22'16	YANG		WEI



NOTES:

- MATERIAL:**
 INSULATOR: HIGH TEMPERATURE THERMO PLASTIC
 FLAMMABILITY RATING: UL94V-0 COLOR: BLACK
 CONTACT: COPPER ALLOYS
 COVER: STAINLESS STEEL
- CONTACT AREA PLATING: GOLD OVER NI**
- SOLDER TAIL COPLANARITY MUST BE WITHIN 0.10MAX.**

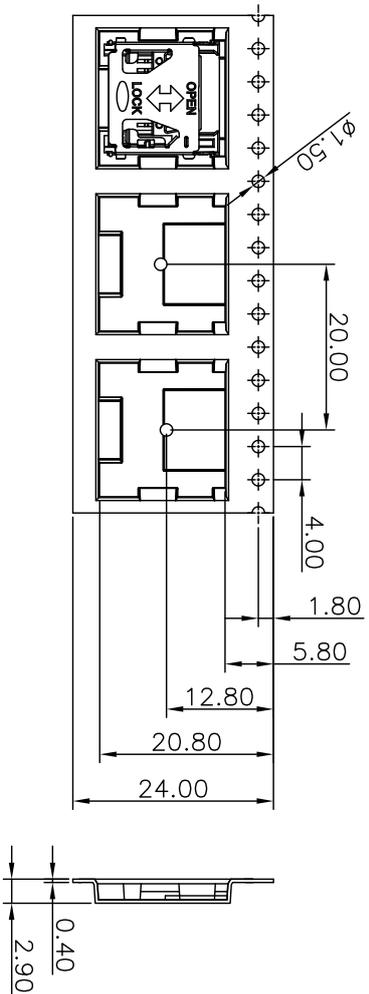


PIN NO.	NAME
#01	DAT2
#02	CD/DAT3
#03	CMD
#04	VDD
#05	CLK
#06	VSS
#07	DAT0
#08	DAT1

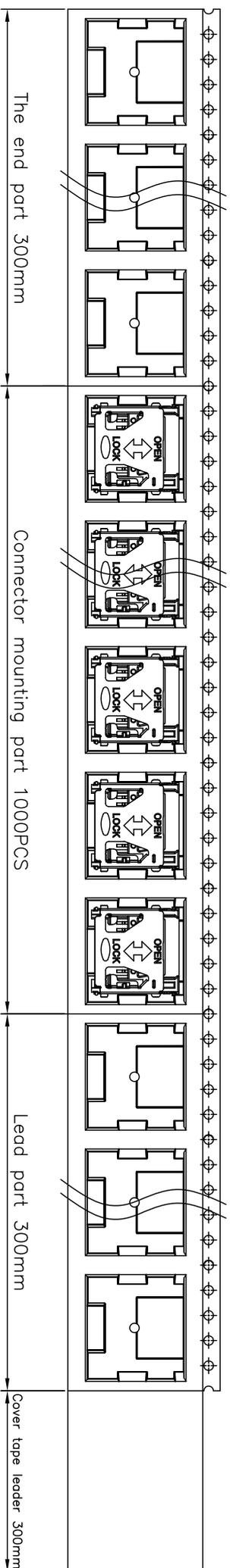
RECOMMENDED PCB LAYOUT(TOP VIEW)
 GENERAL TOLERANCES: ±0.05
 SOLDER AREA

MILLIMETERS	INCH	UNITS	东莞市讯普电子科技有限公司		
X° ± 2'	X° ± 2'	MM			
.X ± 0.30	.XX ± 0.012	MAT'L			
.XX ± 0.20	.XXX ± 0.008	SEE NOTES	PART NUMBER: TF-103		TITLE: MICRO SD HINGE TYPE
.XXX ± 0.10	.XXXX ± 0.004	FINISH	APPD: WEI		DWG NO.:
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF Jin Bi Lai Electronics Group COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF Jin Bi Lai Electronics Group IS PROHIBITED.			CHKD:		
QTY			DR: Yang		
SEE NOTES			SCALE: 1:1		SHEET: 1/2
			REV.:		A0

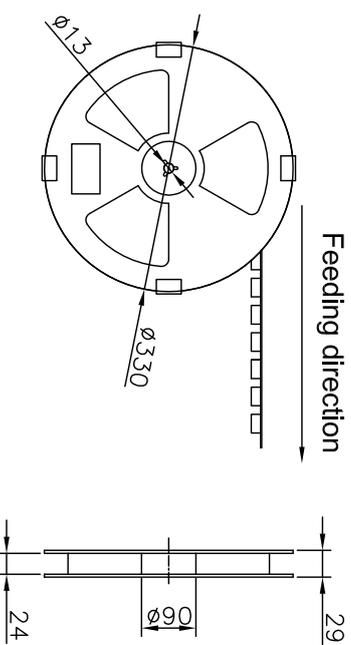
1. Tape packed status



NOTES:
1. CAPABILITY: 1000PCS/REEL



2. Reel packed status



MILLIMETERS	INCH	UNITS	MM
$X^{\circ} \pm 2'$	$X^{\circ} \pm 2'$	MAT'L	
$X \pm 0.30$	$.XX \pm 0.012$	SEE NOTES	
$.XX \pm 0.20$	$.XXX \pm 0.008$	FINISH	
$.XXX \pm 0.10$	$.XXXX \pm 0.004$	SEE NOTES	

DR: Yang	APPD: WEI	CHKD:	QTY	SEE NOTES
PART NUMBER: TF-103		TITLE: MICRO SD HINGE TYPE		
DWG NO.:				

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讯普电子科技有限公司

SCALE	SHEET	REV.
1:1	2/2	A0